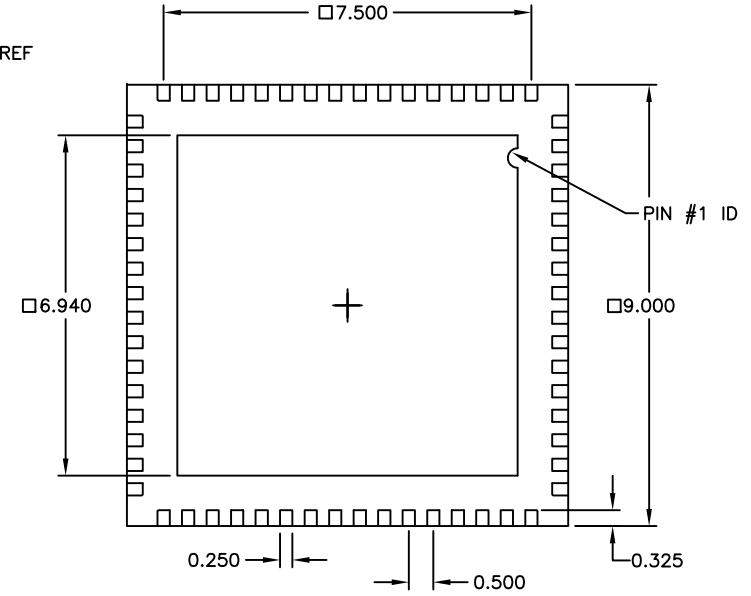
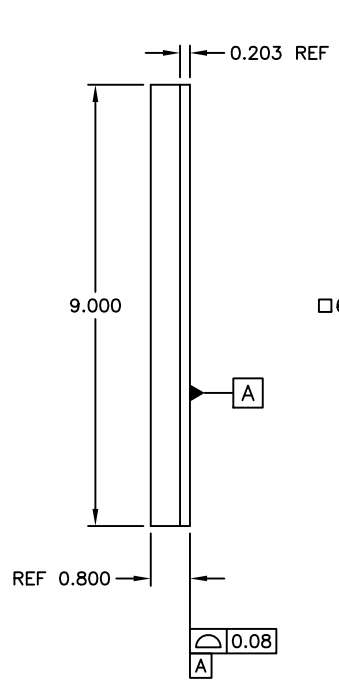
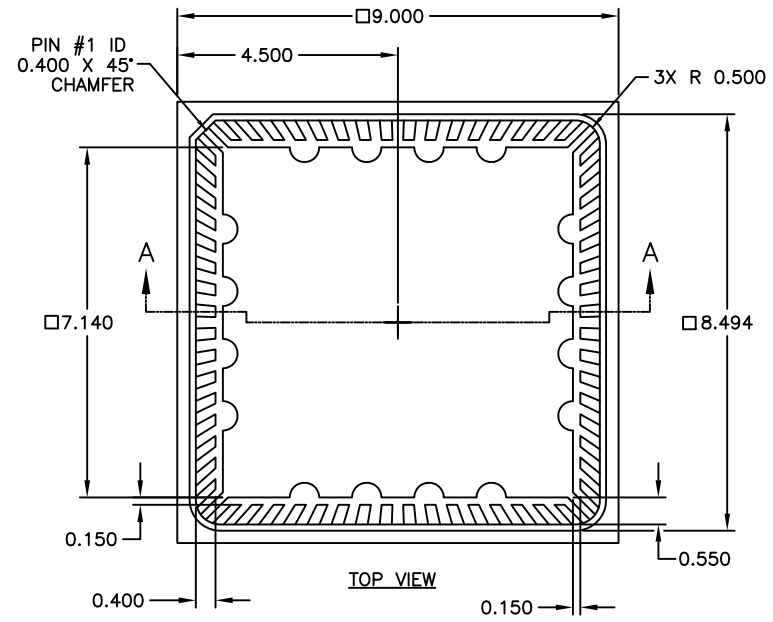
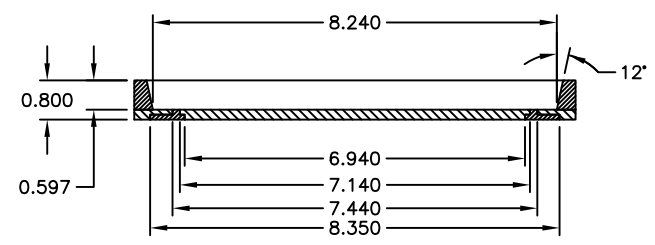


| REVISIONS | | | |
|-----------|----------|-------------|----------|
| ECN NO. | DATE | DESCRIPTION | APPROVED |
| ECN_NO | APP_DATE | ECN_DES | APP_BY |



BOTTOM VIEW



SECTION A-A

NOTES

- MATERIALS:**
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT SPECTRUM FOR DETAILS.
- FINISH:**
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 100 TO 300 MICROINCHES (2.5um - 7.6um) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1um - 2um) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra).
- PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX**
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.**
- PACKAGE CONFORMS TO JEDEC MO-220.**

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER TOLERANCES ARE:

X.XX ± TOL_2PL X.XXXX ± TOL_4PL
X.XXX ± TOL_3PL ANGLE TO ± ANGLE

DO NOT SCALE DRAWING

| | | | |
|----------|----------|------|------------|
| DRAWN BY | DRAWN_BY | DATE | DRAWN_DATE |
| APP BY | APP_BY | DATE | APP_DATE |
| CUSTOMER | | | |

www.spectrum-semi.com
(408) 435-5555
ssm_sales@spectrum-semi.com

| | | |
|-------|----------|----------|
| SIZE | PART NO. | REV |
| A | QFN06402 | |
| SCALE | CAD FILE | CAD_FILE |